

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1-32 (Canceled)

33. (Currently amended) A pre-formed solder mask, comprising:
a film of mask material comprising a polymer and having a substantially uniform thickness; and
at least one open aperture formed through ~~said~~the film, ~~and~~ located correspondingly within
~~said~~the film to a contact pad location of a substrate upon which the pre-formed solder
mask is to be disposed, ~~said at least one open aperture and including a surface~~ configured
to ~~define~~ maintain contact with and form a peripheral shape of a conductive structure to
be formed on ~~said~~the contact pad.

34. (Currently amended) The pre-formed solder mask of claim 33, wherein ~~said~~the at
least one open aperture is configured to be positioned over and to expose a non-peripheral region
of ~~said~~the contact pad.

35. (Currently amended) The pre-formed solder mask of claim 33, wherein ~~said~~the
substantially uniform thickness of ~~said~~the film substantially corresponds to a desired height of
~~said~~the conductive structure.

36. (Currently amended) The pre-formed solder mask of claim 33, wherein ~~said~~the
solder mask material is a polymer.

37. (Currently amended) The pre-formed solder mask of claim 33, wherein ~~said~~the
solder mask material is formulated to shrink or degrade upon exposure to at least one of
radiation, a plasma, and a shrinking agent.

37-40 (Canceled)

41. (Currently amended) The pre-formed solder mask of claim 33, wherein ~~said~~the film is configured to be adhered to a substrate.

42. (Currently amended) The pre-formed solder mask of claim 33, further comprising an adhesive on a surface of ~~said~~the film.

43. (Currently amended) A pre-formed solder mask, comprising:
a film of solder mask material comprising a polymer and having a substantially uniform thickness, ~~said~~the film including a surface configured to be adhered to a substrate; and
at least one open aperture formed through ~~said~~the film, ~~and~~ located correspondingly within ~~said~~the film to a contact pad location of a substrate upon which the pre-formed solder mask is to be disposed, ~~said at least one open aperture and including a surface~~ configured to maintain contact with and define a peripheral shape of a conductive structure to be formed on ~~said~~the contact pad.

44. (Currently amended) The pre-formed solder mask of claim 43, wherein ~~said~~the at least one open aperture is configured to be positioned over and to expose a non-peripheral region of ~~said~~the contact pad.

45. (Currently amended) The pre-formed solder mask of claim 43, wherein ~~said~~the substantially uniform thickness of ~~said~~the film substantially corresponds to a desired height of ~~said~~the conductive structure.

46. (Currently amended) The pre-formed solder mask of claim 43, wherein ~~said~~the solder mask material is a polymer.

47. (Currently amended) The pre-formed solder mask of claim 43, wherein ~~said~~the solder mask material is formulated to shrink or degrade upon exposure to radiation, a plasma, or a shrinking agent.

48. (Currently amended) The pre-formed solder mask of claim 43, wherein ~~said~~the surface of ~~said~~the film includes an adhesive material.

49. (Currently amended) A semiconductor device assembly, comprising:
a substrate including at least one contact pad;
a pre-formed film of solder mask material comprising a polymer and disposed on ~~said~~the substrate, ~~said~~the pre-formed film having a substantially uniform thickness; and
at least one open aperture formed through ~~said~~the pre-formed film, ~~and located correspondingly within said~~the film to ~~said~~the at least one contact pad, ~~said at least one open aperture and configured to define form a peripheral shape of a conductive structure to be formed therein.~~

50. (Currently amended) The semiconductor device assembly of claim 49, further comprising a conductive structure substantially filling ~~said~~the at least one open aperture and in communication with ~~said~~the at least one contact.

51. (Currently amended) The semiconductor device assembly of claim 50, wherein ~~said~~the conductive structure protrudes beyond an exposed surface of ~~said~~the pre-formed film.

52. (Currently amended) The semiconductor device assembly of claim 49, wherein ~~said~~the at least one open aperture is positioned over and exposes a non-peripheral region of ~~said~~the at least one contact pad.

53. (Currently amended) The semiconductor device assembly of claim 49, wherein ~~said~~the substantially uniform thickness of ~~said~~the pre-formed film is substantially equal to a height of ~~said~~the conductive structure.

54. (Currently amended) The semiconductor device assembly of claim 49, wherein ~~said~~the solder mask material is a polymer.

55. (Currently amended) The semiconductor device assembly of claim 49, wherein ~~said~~the solder mask material is formulated to shrink or degrade upon exposure to at least one of radiation, a plasma, and a shrinking agent.

56. (Currently amended) The semiconductor device assembly of claim 49, wherein ~~said~~the surface of ~~said~~the pre-formed film includes an adhesive material.